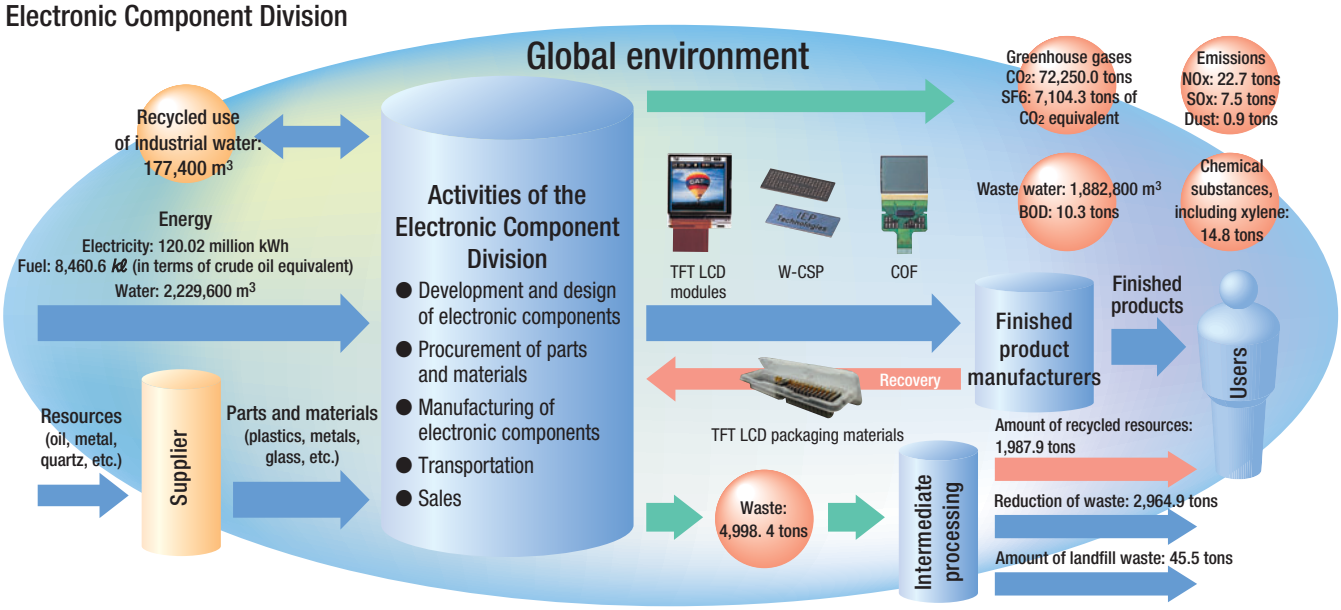
The Casio Group's Inputs and Outputs

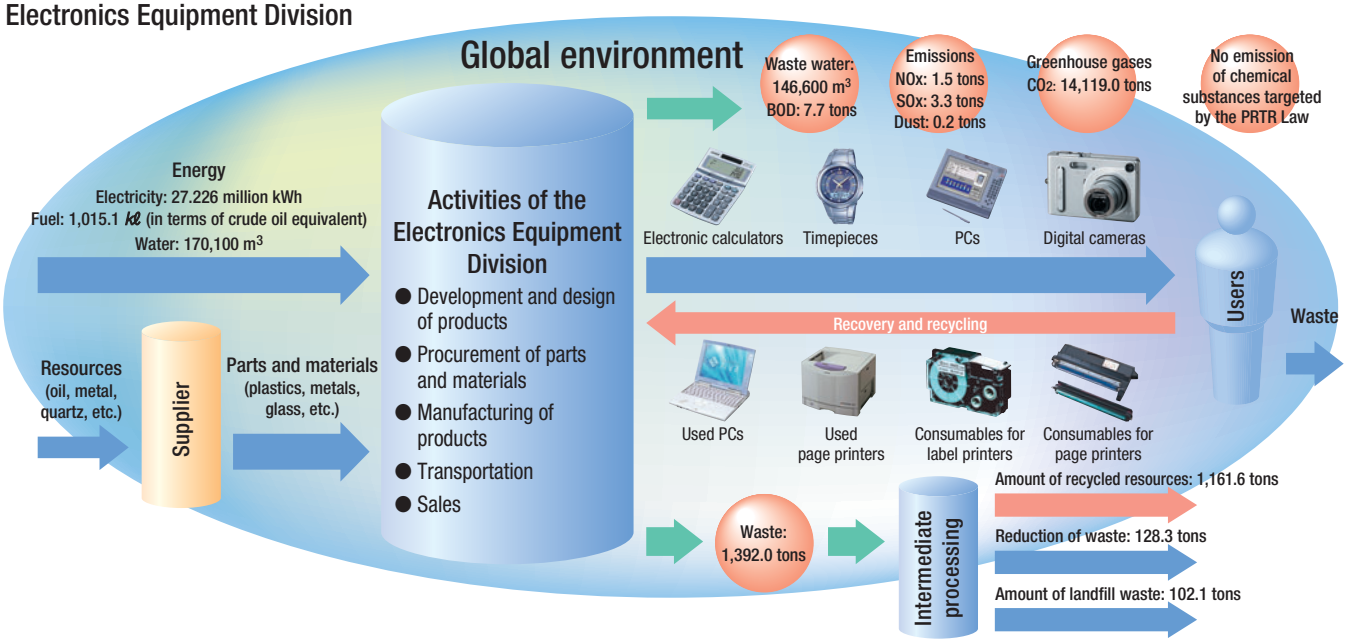
Casio's business operations are divided into the Electronic Component Division and the Electronics Equipment Division. We measured the environmental impact caused by these divisions, referring to what substances and energy sources they input for their activities and what were emitted or generated as a result.

*The Electronic Component Division is composed of four domestic sites, while the Electronic Equipment Division is composed of eight domestic sites.

Electronic Component Division



Electronics Equipment Division



The major products of the Casio Group's Electronic Component Division include TFT LCD modules manufactured by Kochi Casio, W-CSP and COF produced by Casio Micronics, and LCDs manufactured by Kofu Casio. These companies have clean rooms that meet the requirements for fine processing, pure water cleaning systems, and wastewater processing facilities. As a result, these companies alone account for approximately 80% of the energy consumed by the entire Casio Group and they also use more water and chemicals than the companies and sites belonging to the Electronics Equipment Division.

At our manufacturing factories, we have implemented aggressive measures for energy conservation and water saving. For example, at the factory of Casio Micronics, use of clean water was significantly reduced through the use of recycled wastewater from the cleaning process.

The companies belonging to the Electronics Equipment Division have transferred some of their production facilities overseas, including to China, but are still domestically manufacturing such items as digital cameras, cellular phones, and page printers. Production of these products requires advanced assembly technologies and significant levels of energy as well. We have therefore introduced energy conservation and resource saving to the product assessment criteria to be conducted at the product design stage, thereby promoting the development of environmentally-friendly products. At the same time, we encourage each of our factories to devise their own unique methods for energy conservation.

Glossary

W-CSP (Wafer-level Chip Size Package)
W-CSP represents an advanced LSI packaging technology. The LSI package is finished on a wafer by redistribution of pads, forming terminals, and sealing by resin. This technology made it possible to downsize the LSI package into the size of the chip.

COF
Chip-on-film. A method of directly joining an LSI chip to a thin resin film to achieve efficient, high-density packaging of LSI circuits in a limited space.